AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/775,890

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Filing Date: February 9, 2004

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE

Assignee: Intel Corporation

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, line 7 is amended as follows:

The present application is a divisional of application U.S. Serial No. 09/652,430, filed on August 31, 2000, now issued as U.S. Patent No. 6,724,078, which is incorporated herein by reference.